

**PATENT ASSIGNMENT**

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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
<b>CONVEYING PARTY DATA</b>											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Satoru HANZAWA</td> <td>01/20/2010</td> </tr> <tr> <td>Fumihiko NITTA</td> <td>01/22/2010</td> </tr> <tr> <td>Nozomu MATSUZAKI</td> <td>01/21/2010</td> </tr> <tr> <td>Toshihiro TANAKA</td> <td>01/25/2010</td> </tr> </tbody> </table>		Name	Execution Date	Satoru HANZAWA	01/20/2010	Fumihiko NITTA	01/22/2010	Nozomu MATSUZAKI	01/21/2010	Toshihiro TANAKA	01/25/2010
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<b>RECEIVING PARTY DATA</b>											
Name:	Renesas Technology Corp.										
Street Address:	6-2, Otemachi 2-chome, Chiyoda-ku										
City:	Tokyo										
State/Country:	JAPAN										
<b>PROPERTY NUMBERS Total: 1</b>											
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>12672685</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	12672685						
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Application Number:	12672685										
<b>CORRESPONDENCE DATA</b>											
Fax Number:	(703)610-8686										
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Phone:	7036108652										
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ATTORNEY DOCKET NUMBER:	XA-11542/T3381-17631US01										
NAME OF SUBMITTER:	Mitchell W. Shapiro										
Total Attachments: 2 source=assignment#page1.tif source=assignment#page2.tif											

CH \$40.00 12672685

# ASSIGNMENT

(讓渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Renesas Technology Corp., a corporation organized under the laws of Japan, located at 6-2, Otemachi 2-chome, Chiyoda-ku, Tokyo, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said Renesas Technology Corp., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

## SEMICONDUCTOR DEVICE AND ITS MANUFACTURING METHOD

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted,

to be held and enjoyed by said Renesas Technology Corp.,

its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Renesas Technology Corp.

Signed on the date(s) indicated aside our signatures:

	INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1)	<u>Satoru Hanzawa</u> (Satoru HANZAWA)	<u>1/20/2010</u>
2)	_____ (Fumihiko NITTA)	_____
3)	<u>Nozomu Matsuzaki</u> (Nozomu MATSUZAKI)	<u>1/21/2010</u>
4)	<u>Toshihiro Tanaka</u> (Toshihiro TANAKA)	<u>1/25/2010</u>
5)	_____	_____
6)	_____	_____

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INVENTOR(S)  
(発明者フルネームサイン)

Date Signed  
(署名日)

1) \_\_\_\_\_ (Satoru HANZAWA)

2) Fumihiko Nitta \_\_\_\_\_ (Fumihiko NITTA)

3) \_\_\_\_\_ (Nozomu MATSUZAKI)

4) \_\_\_\_\_ (Toshihiro TANAKA)

5) \_\_\_\_\_

6) \_\_\_\_\_

\_\_\_\_\_  
1/22/2010

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